

<b>Notification Number:</b>	20200625006	<b>Notification Date:</b>	June 29, 2020
<b>Title:</b>	Datasheet for AMC1300		
<b>Customer Contact:</b>	PCN Manager	<b>Dept:</b>	Quality Services
<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

**Notification Details**

**Description of Change:**

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



**AMC1300**

SBAS895B – MAY 2018 – REVISED APRIL 2020

**Changes from Revision A (June 2018) to Revision B**

**Page**

• Changed <i>DIN V VDE V</i> to <i>DIN VDE V</i> in <i>Safety-related certifications</i> Features bullet.....	1
• Changed CLR and CPG parameter values from 9 mm to 8.5 mm in <i>Insulation Specifications</i> table.....	7
• Changed <i>Insulation Specifications</i> table per ISO standard .....	7
• Changed <i>Safety-Related Certification</i> table per ISO standard.....	8
• Changed $P_S$ equation details in <i>Safety Limiting Values</i> table .....	8
• Added <i>Input Offset Voltage vs Temperature</i> figure .....	13
• Added <i>Common-Mode Rejection Ratio vs Input Frequency</i> figure .....	14
• Added <i>Gain Error vs Temperature</i> figure .....	15
• Added <i>Gain Error Drift Histogram</i> figure .....	15
• Changed <i>Do's and Don'ts</i> section title to <i>What to Do and What Not to Do</i> .....	25

The datasheet number will be changing.

Device Family	Change From:	Change To:
AMC1300	SBAS895A	SBAS895B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/AMC1300>

**Reason for Change:**

To accurately reflect device characteristics.

**Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):**

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

**Changes to product identification resulting from this notification:**

None.

**Product Affected:**

AMC1300BDWV	AMC1300BDWVR	AMC1300DWV	AMC1300DWVR
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For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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